TE Internal #: 171825-4

PCB Mount Header, Vertical, Wire-to-Board, 4 Position, 2.5 mm [.

098 in] Centerline, Partially Shrouded, Tin (Sn), Through Hole -

Solder, Signal

View on TE.com >

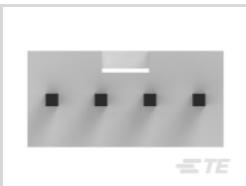


Connectors > PCB Connectors > PCB Headers & Receptacles











PCB Connector Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Wire-to-Board

Number of Positions: 4

Centerline (Pitch): 2.5 mm [.098 in]

Features

Product Type Features

PCB Connector Type	PCB Mount Header
Connector System	Wire-to-Board
Header Type	Partially Shrouded
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly

Configuration Features

PCB Mount Orientation	Vertical
Number of Positions	4
Number of Rows	1

Body Features

Contact Features

Mating Square Post Dimension	.64 mm[.025 in]
Contact Mating Area Plating Material	Tin (Sn)



Contact Mating Area Plating Material Thickness	.8 μm[31.49 μin]
Contact Current Rating (Max)	3.5 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
PCB Mount Alignment	Without
Mating Retention	With
PCB Mount Retention	Without
Connector Mounting Type	Board Mount
Mating Alignment	With
Housing Features	
Centerline (Pitch)	2.5 mm[.098 in]
Housing Material	Brass
Usage Conditions	
Operating Temperature Range	-20 - 95 °C[-4 - 203 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Bag

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	有害物质含量符合标准要求 No Restricted Substance(s) Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2025 (250)



Candidate List Declared Against: JUNE

2025 (250)

Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F < 900 ppm per
homogenous material. Also BFR/CFR/PVC
Free

Solder Process Capability Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts







Customers Also Bought























Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_171825-4_Y2.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_171825-4_Y2.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_171825-4_Y2.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

1-1773972-5_EIS_Connectors_Brochure

English

Product Specifications

Crimping of AMP El Series Connector Contacts

Japanese

Application Specification

Japanese

Agency Approvals

Agency Approval Document

English

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PCB Mount Header, Vertical, Wire-to-Board, 4 Position, 2.5 mm [.098 in] Centerline, Partially Shrouded, Tin (Sn), Through Hole - Solder, Signal

